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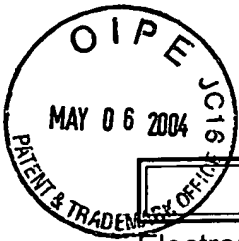
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Application ID: 10626150
Title of Invention: PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE
First Named Inventor: THOMAS GLENN
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-07-24
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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE						
<p>Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P. Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2</p>							
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
Submitted by:	Elec. Sign.	Sign. Capacity					
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney					
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids4-usidst.xml us-ids.dtd us-ids.xsl</td></tr></table>		Documents being submitted	Files	us-ids	ids4-usidst.xml us-ids.dtd us-ids.xsl		
Documents being submitted	Files						
us-ids	ids4-usidst.xml us-ids.dtd us-ids.xsl						
Comments							



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
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Title of Invention

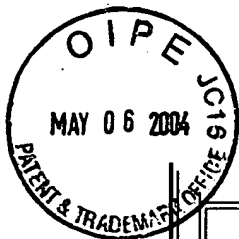
PLASTIC INTEGRATED CIRCUIT PACKAGE AND
AND LEADFRAME FOR MAKING THE PACKAGE

Application Number: 10/626150
Confirmation Number: 9302
First Named Applicant: THOMAS GLENN
Attorney Docket Number:AMKOR007C2
Art Unit: 2815
Search string: (5886398 or 5894108 or 5897339 or 5900676 or
5903049 or 5903050 or 5909053 or 5915998 or
5917242 or 5939779 or 5942794 or 5951305 or
5959356 or 5969426 or 5973388 or 5976912 or
5977613 or 5977615 or 5977630 or 5981314 or
5986333 or 5986885 or 6001671 or 6013947 or
6018189 or 6020625 or 6025640 or 6031279 or
6034423 or RE36613 or 6040626 or 6043430 or
6060768 or 6060769 or 6072228 or 6075284 or
6081029 or 6084310 or 6087715 or 6087722 or
6100594 or 6114752 or 6113474 or 6118174 or
6118184 or 6130115 or 6130473 or RE36907 or
6133623 or 6140154).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date